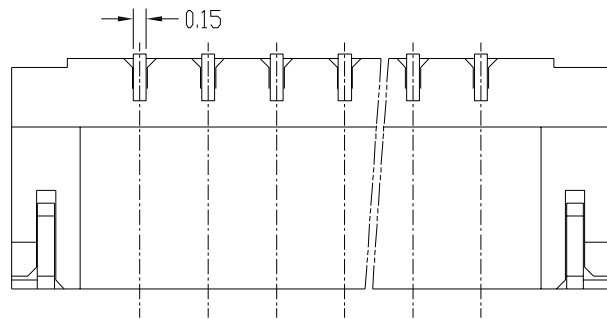


PCB LAYOUT

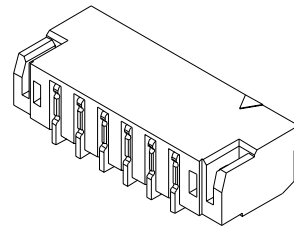
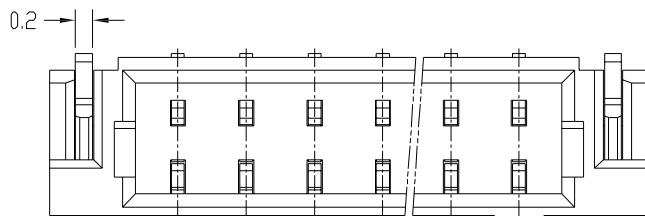
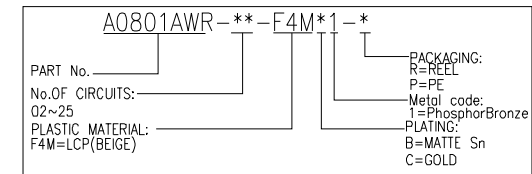


15	11.2	14.2			
14	10.4	13.4			
13	9.6	12.6			
12	8.8	11.8			
11	8.0	11.0	25	19.0	22.0
10	7.2	10.2	24	18.2	21.2
9	6.4	9.4	23	17.4	20.4
8	5.6	8.6	22	16.6	19.6
7	4.8	7.8	21	15.8	18.8
6	4.0	7.0	20	15.0	18.0
5	3.2	6.2	19	14.2	17.2
4	2.4	5.4	18	13.4	16.4
3	1.6	4.6	17	12.8	15.8
2	0.8	3.8	16	12.0	15.0
孔位	DIM A	DIM B	孔位	DIM A	DIM B

主要技术参数 Main Specifications

- 线 数 (Poles): 02 to 25
- 接触电阻 (Contact resistance):  $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance):  $\geq 100M\Omega$
- 额定电压 (Rated voltage): 30V AC DC
- 额定电流 (Rated current): 0.5A AC DC
- 耐 电压 (Withstand Voltage): 200V AC/minute
- 温度范围 (Temperature Range):  $-25^{\circ}C \sim +85^{\circ}C$

ORDER INFORMATION:



C	Solder TAB	2 PCS	PhosphorBronze	Matte Sn-plated
B	CONTACT	n PCS	PhosphorBronze	Matte Sn-plated/GOLD
A	HOUSING	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH

UNITS  
mm

MAT'L

FINISH

APPD:

CHKD:

DR: HU 2016.09.28

Q'TY  
PCS

**MSTCONN**

PART NO.(INTENDED USE)

A0801AWR-\*\*-F4M\*1-\*

APPD:

CHKD:

DR: HU 2016.09.28

深圳市德瑞电子有限公司  
SHENZHEN DERUI ELECTRONIC CO.,LTD.

TITLE:  
0.8mmPITCH 90°WAFER SMT TYPE

DWG NO.:

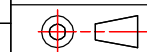
QWY-GCCP-0705

SCALE

SHEET

REV. A

X.± 0.3	X°.± 5°
.X± 0.25	.X°.± 2°
.XX± 0.20	.XX°.± 1°
.XXX± 0.10	.XXX°.± 0.5°



1/1	1/1	A
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